

ABSTRACT

The present invention discloses a liquid storage device and an electroplating apparatus. The liquid storage device comprises a tank body including multiple working cycle drain ports for supplying solution to multiple work chambers and a thermal cycle liquid injection port for introducing heated solution into the tank body. The working cycle drain ports are located on opposing side walls of the tank body. A side wall connecting the two side walls has the thermal cycle liquid injection port positioned near or at the middle of the length of the side wall. The liquid storage device further comprises a guide element located inside the tank body. The guide element is connected to the thermal cycle liquid injection port, allowing the solution entering from the thermal cycle liquid injection port to flow through the guide element into the tank body and toward each of the working cycle drain ports. This invention has the advantage of equalizing the temperature and flow rate of the solution entering different work chambers through a single liquid storage device.